

All parts are screened per MIL-PRF-19500, JANTX Level and the device detail specification. All testing is performed at room temperature, unless indicated otherwise. For testing at high and low temperatures, Group A testing is required.

	<b>Test</b>	<b>Method</b>	<b>Conditions / Notes</b>
<b>1</b>	<b>Temperature Cycling</b>	<i>MIL-STD-750 Method 1051</i>	Test condition C or maximum storage temperature, whichever less. 20 cycles, 10 minutes per extreme.
<b>2</b>	<b>Surge Test</b>	<i>MIL-STD-750 Method 4066</i>	Rated $I_{FSM}$ as specified in the detail drawing.
<b>3</b>	<b>Thermal Impedance</b>	<i>MIL-STD-750 Method 3101</i>	As specified in the detail drawing.
<b>4</b>	<b>High Temperature Reverse Bias Burn-in (HTRB)</b>	<i>MIL-STD-750 Method 1038</i>	Condition A. 80% of rated $V_R$ for 48 hours at 150°C.
<b>5</b>	<b>Interim Electrical Testing</b>		DC parameters per device detail specification.
<b>6</b>	<b>Power Burn-in</b>	<i>MIL-STD-750 Method 1038</i>	96 hours of forward bias per device detail specification.
<b>7</b>	<b>Final Electrical Testing</b>		DC parameters per device detail specification.
<b>8</b>	<b>Delta Calculation</b>		Delta parameters and limits per device detail specification.
<b>9</b>	<b>PDA Calculation</b>		10 percent defective allowed.
<b>10</b>	<b>Seal Test Gross Leak</b>	<i>MIL-STD-750 Method 1071</i>	Condition C

**Notes:**

1. Testing varies in accordance with the device detail specification.
2. Specific customer testing needs may be accommodated into any testing flow (selection tests, temperature requirements, special tests).